

Preface

The present volume contains selected papers from the 12th International Manufacturing Conference in China (IMCC2006). The conference is organized by Northwestern Polytechnical University.

IMCC is a bi-annual conference inaugurated in 1983. The past eleven IMCC conferences were successfully held in Guangzhou (twice), Wuhan, Nanjing, Beijing, Harbin, Hong Kong, Singapore, Xiamen, and Jinan. They have provided excellent platforms for participants to exchange their new ideas and have brought forth new research opportunities and collaborations. With the support of National Natural Science Foundation of China and European Commission Asia Link Programme, the IMCC 2006 sponsored by Northwestern Polytechnical University, The Hong Kong Polytechnic University, National University of Singapore, University of Warwick and University of Strathclyde will be held in Xi'an, China, during September 21-23, 2006.

This volume presents a selection of 293 papers from over 500 papers submitted to the conference from universities and industries all over the world. All of the papers have been peer reviewed by picked experts. The papers selected for this volume depended on their quality and their relevancy to the conference. I hope this volume will provide the readers a broad overview of the recent advances in the field of materials manufacturing technology.

I wish to express our sincere appreciation and thanks to all the members of the IMCC2006 Conference Organizing Committee and Academic Committee, the Program Committee and all the referees, chairs, staffs, volunteers for their tremendous efforts. Without their hard work and excellent jobs, it was impossible to lead to the success of IMCC2006 and this special issue.

I am grateful to over 80 referees from Tshinghua University, Shanghai Jiaotong University, Harbin Institute of Technology, South China University of Technology, Nanjing University of Aeronautics and Astronautics, Xi'an Jiaotong University, Dalian University of Technology, Shandong University, Guangdong University of Technology, Chongqing University, Tianjing University, Beijing Institute of Technology, Huaqiao University, Beijing University of Aeronautics and Astronautics, Jiangsu University and Northwestern Polytechnical University for their strict reviews which guaranteed the quality of IMCC2006 and this volume.

I am grateful to all the members of the organization committee of IMCC2006: Prof. Geng Liu, Prof. Dinghua Zhang, Ms. Jingting Yuan, Prof. Liyan Wu, Ms. Xinyu Liu, Ms. Bo Chang, Ms. Dan Xiang, and Prof. Quan Zhou. Without their diligent work and countless contribution, it would be unthinkable that we may have the success of IMCC2006 and this volume.

I also wish to thank the chairs of the scientific panels: Prof. Hua Tao, Prof. Weihong Zhang, Prof. Songzheng Zhao and Prof. Shusheng Zhang, and the secretaries of the scientific panels: Dr. Yongjun Wang, Dr. Kepeng Qiu, Dr. Shubin Shi and Dr. Kaifu Zhang for their contribution to the high-standard technical programme.

Especially, I am most grateful to Prof. W. B. Lee and Dr. Sandy To of Hong Kong Polytechnic University for the fruitful cooperation. Deeply gratitude also given to all other persons who took care of and helped this conference and this special issue, especially Prof. Yuanzhong Lei from National Natural Science Foundation of China, for his support during the whole course of the conference, not only to the call and the reviewing process, but also to the publication and numerous other issues. Thanks are also given to Prof. Ning He of Nanjing University of Aeronautics and Astronautics for his discussion and help in organizing the conference.

Furthermore, I am deeply indebted to Prof. Xipeng Xu, vice President of Huaqiao University for his efforts at each stage of the conference. Without his dedicational efforts, this volume would not be possible. In this regard, thanks are also given to Mr. Guoqin Huang of Huaqiao University for his tremendous work to make the selected papers in this issue fit the requirement for publication, and Trans Tech Publications for producing the volume.

Finally, I would like to thank all the authors for their contribution to this valuable special issue.

Prof. Chengyu Jiang

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